Switching Regulators (Integrated FET)

3.3V and 5V output Low Iq DC/DC Converters

BD99010EFV-M BD99011EFV-M

General Description

The BD99010EFV-M and BD99011EFV-M are ultra low Iq Step-down DC/DC converters with integrated power MOSFETs for 3.3V and 5V, respectively.
The SLLMTM (Simple Light Load Mode) control ensures an ultra low quiescent current and high efficiency at low load situation as well as a high efficiency at high load situations while maintaining a regulated output voltage.
The product is compliant with automotive standards and accommodates a maximum voltage of 42V. The minimum input voltage is 3.6 V in order to sustain output at cold cranking conditions. The current mode regulation loop gives a fast transient response and easy phase compensation.
The BD99010EFV-M and BD99011EFV-M are available in a HTSSOP-B24 package. In an application it requires a small number of external components and small PCB footprint.

Features

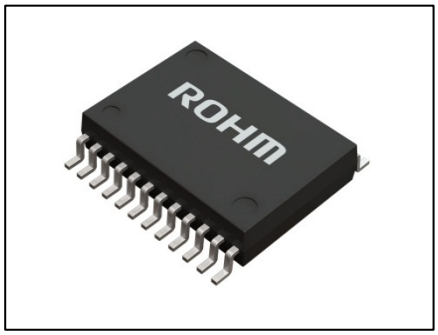
- Low Quiescent Operating Current: 22µA
- Simple Light Load Mode (SLLM)
- Supports Cold Cranking Down to 3.6V
- Output Voltage Accuracy: ±2%
- Synchronous Rectifier
- Soft Start
- Chip Enable pin compatible with CMOS logic and battery voltages
- Forced PMW Mode Function
- Current Mode Control with External Compensation Circuit
- Over Current Protection, Short Circuit Protection, Over Voltage Protection for VOUT, Under Voltage Lock Out for VIN and Thermal Protection Circuits

Key Specifications

- Input Voltage Range: 3.6V to 35V (Absolute Maximum42V) (Initial startup is over 3.9V)
- Output Voltage Range: 3.3V (BD99010EFV-M) 5V (BD99011EFV-M)
- Switch Output Current: 2A(Max)
- Switching Frequency: 200kHz to 500kHz
- Pch FET ON Resistance: 170mΩ(Typ)
- Nch FET ON Resistance: 130mΩ(Typ)
- Operating Temperature Range: -40°C to +105°C
- AEC-Q100 Qualified

Package

	W(Typ) x D(Typ) x H(Max)
HTSSOP-B24	7.80mm x 7.600mm x 1.00mm



Applications

- Automotive Battery Powered Supplies(Cluster Panel, Car Multimedia)
- Industrial/Consumer Supplies.

Typical Application Circuit

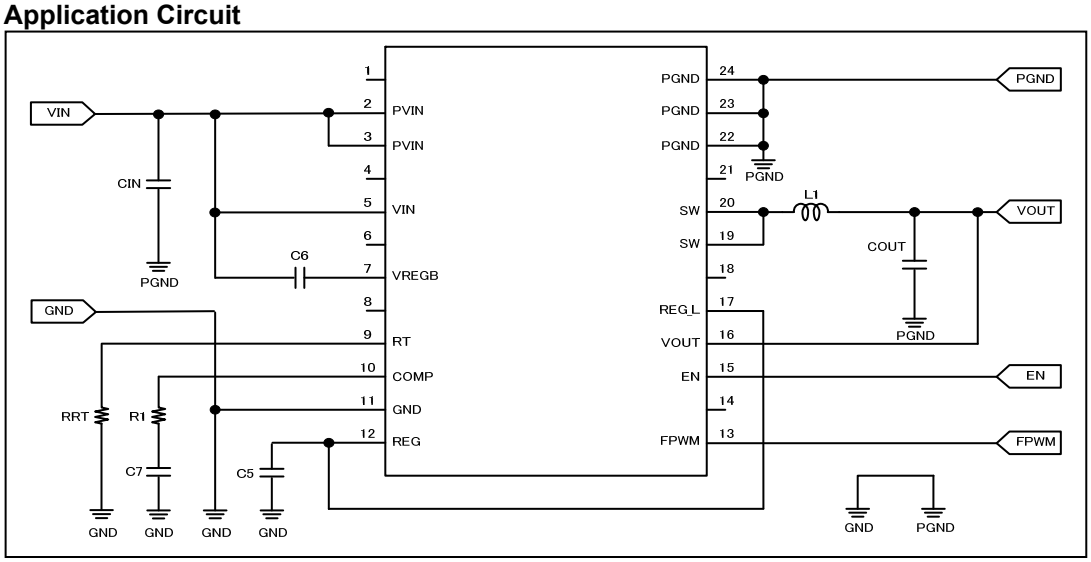


Figure1. Reference application circuit

○Product structure：Silicon monolithic integrated circuit ○This product is not designed protection against radioactive rays

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Pin Configuration

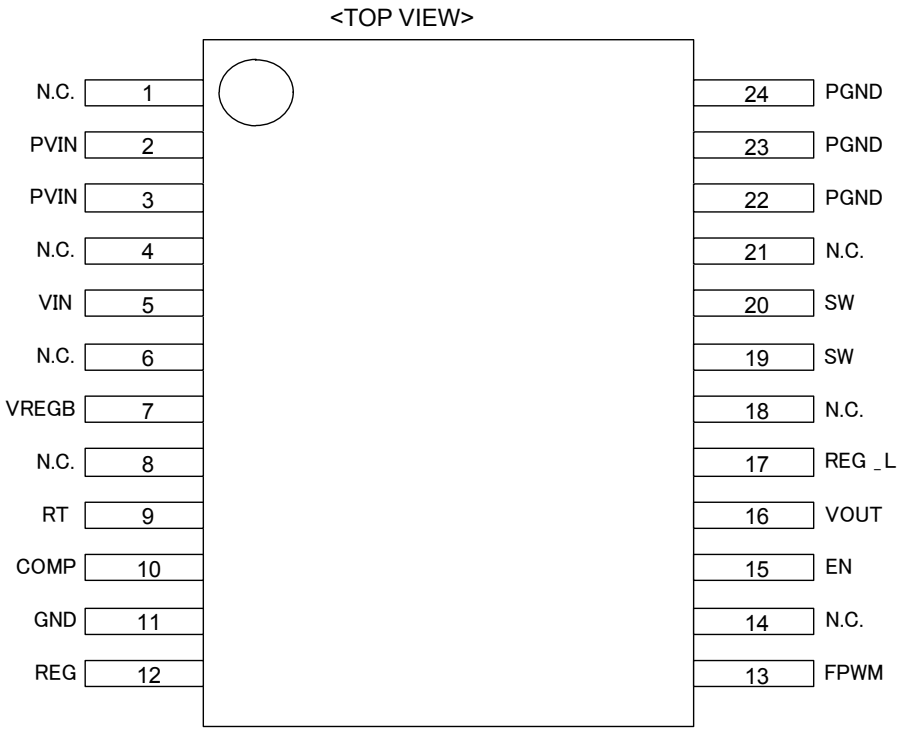


Figure 2. Pin configuration

Pin Description

Pin No.	Pin Name	Function	Pin No.	Pin Name	Function
1	N.C.	No connection	13	FPWM	Forced PWM mode pin
2	PVIN	Power input supply pin	14	N.C.	No connection
3	PVIN	Power input supply pin	15	EN	Enable pin, active high
4	N.C.	No connection	16	VOUT	Output pin
5	VIN	Input supply pin	17	REG_L	Internal logic supply pin
6	N.C.	No connection	18	N.C.	No connection
7	VREGB	FET driver drive power supply pin	19	SW	Switching output pin
8	N.C.	No connection	20	SW	Switching output pin
9	RT	Switching frequency setting pin	21	N.C.	No connection
10	COMP	Error amplifier output pin	22	PGND	Power GND pin
11	GND	GND pin	23	PGND	Power GND pin
12	REG	Internal regulator output pin	24	PGND	Power GND pin

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Block Diagram

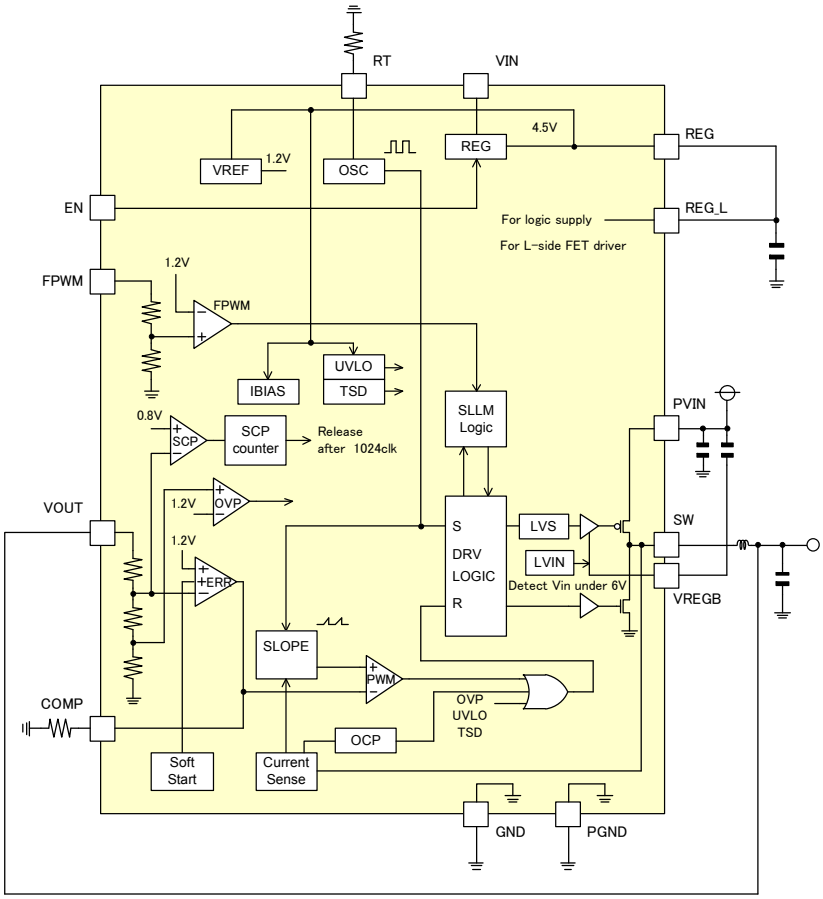


Figure 3. Block diagram

Description of Blocks

(1) Internal regulator voltage (REG)

This block generates the 4.5V supply of the internal circuitry. This function requires an external buffer capacitor connected to the REG pin. Also the supply voltage has to be connected to the logic supply via the REG_L pin. A ceramic capacitor with of 1µF or more or with low ESR with short leads to the REG, REG_L pin and ground is recommended.

(2) Enable

By setting EN below 0.8V, the device can be set in stand-by mode. When the stand-by mode is activated, almost all internal circuits are switched off to reduce the current consumption from the power supply to 1µA (25°C, typ.). Because the EN pin is not pulled-down internally, in order to set the device in standby the EN pin has to be connected to GND or supplied with the voltage below 0.8V. Moreover, EN sink current is below 0.1µA for voltages to approximately 14V.

(3) FPWM

By setting FPWM pin more than 2.0V, the device switches to forced PWM mode and operates as normal synchronous type DC/DC converter ie. no pulse skipping at low load conditions. With FPWM is disabled, the quiescent current is very low but the step response is slow for large load step. With FPWM is enabled, the quiescent current is larger but the step response is fast for large load step. Note that when the mode is changing from SLLM to FPWM mode there will be an undershoot / over shoot. See Figure 27 on page 13 and Figure 31 on page 14.

(4) Soft start

This block provides a function to prevent the overshoot of the output voltage: VOUT and/or large inrush currents by controlling the error amplifier input voltage and increasing switching pulse width gradually at start up. The soft start time is set to 6ms (typ.). At low output load conditions with FPWM is enabled, the soft start generates some noise on the output voltage during sweep up to about 2 volts. This phenomenon can be avoided by adding a small series resistance in the output buffer capacitor.

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(5) Error amplifier
The error amplifier compares the output feedback voltage to the 1.2V internal reference voltage and outputs the difference as current to the COMP pin, which voltage is used to determine the switching duty cycle. A t initial startup when the soft start works, the COMP voltage is limited to the soft start voltage. Moreover, the external resistor and capacitor are required to COMP pin as phase compensation circuit.

(6) PWM modulator.
The PWM modulator converts the voltage at the COMP terminal to a continuous variable duty cycle that controls the output power transistors. At very low input voltages the duty cycle can become 1 indicating the high-side power transistor continuously in on-state. At very high input voltages the duty cycle becomes very small but limited at an on-time of about 200ns. It should be noted that at high oscillation frequency settings this could lead to random pulse skipping. For instance at 500 kHz the duty cycle is limited to values larger than 200ns / 2µs = 10%. This means that for 3.3V output the input voltage is limited to 33 V when avoiding random pulse skips. In case, a higher input voltage is required the switching frequency has to be chosen lower.

(7) Oscillator
The oscillation frequency is determined by the current going through the external resistor RT at constant voltage of ca. 0.3V. The frequency can be set in the range between 200kHz to 500kHz. It should be noted that the frequency increases ca. 10% when the input voltage VIN is lower than 4.5 V because in that condition the internal supply voltage VREG is also lowered.

(8) VREGB pin and Low input voltage detection (LVIN)
VREGB is the supply voltage of the high-side driver and output power transistor. VREGB voltage is referenced from PVIN at voltage with 7.2V (typ.). When VIN voltage becomes below 6V (typ.), the LVIN circuit is activated and VREGB is shorted to GND. By doing so the output power transistor is driven with the full supply voltage at cold cranking conditions.
An external capacitor is required between PVIN and VREGB pin. A ceramic capacitor with 0.1µF or low ESR type is recommended.

(9) Overcurrent protection (OCP)
The overcurrent protection is activated when the SW current exceeds 3.3A (typ.). Once activated the ON duty cycle will be limited and the output voltage lowered.

(10) Short circuit protection (SCP) and SCP counter
The short circuit protection is activated after the output voltage (FB voltage) drops below 67% of the nominal voltage level and the overcurrent protection is activated (except during startup). This indicated an output short and the short circuit protection will be activated.
When the short circuit protection is activated, for a period of 1024 cycles of oscillation frequency, switching will be terminated by turning off the output transistors and the SS and COMP pins discharged. After this time out period the switching will resume including soft start.

(11) Under voltage lockout circuit (UVLO)
If the VIN drops below 3.4V (typ.) the UVLO is activated and the BD99010 and BD99011 is turned off.

(12) Thermal shutdown (TSD)
If the chip temperature (Tj) reaches or exceeds ca. 175°C (typ.) the output is turned off. Switching will resume with soft start when the temperature drops below ca. 150 °C (typ.)

(13) Over voltage protection(OVP)
The BD9901x is equipped with an integrated over voltage protection (OVP) for output voltages exceeding 10% above nominal output voltage. The OVP terminates switching until the output voltage drops below nominal value again before resuming normal operation. The OVP is intended as a last-resort protection mechanism and should never trigger in well-designed applications. Essentially there are two main root causes for an OVP event in a practical application:

- Extremely fast and extreme input voltage variations, for instance a supply voltage step from a few volts to a maximum of 36V in a few micro seconds. Normally, an appropriate input filter should prevent this from occurring.
- Extreme load current variations from maximum current to zero in very short time, for instance caused by a mechanical fuse or relay to trip.

Also it should be noted that when the output load is zero for a longer time while the ambient temperature is extremely high (above 105ºC) a small leakage current through the high-side switch inside the BD9901x can cause the output voltage to be higher than the OVP level. In case this might happen in the application under extraordinary conditions, it is advised to bleed a small output current exceeding this leakage. Naturally, this current increases the ultra-low quiescent current of 22 µA of a typical BD9901x application.

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Operation

The BD99010EFV-M and BD99011EFV-M are a synchronous rectifying step-down switching regulator with fast transient response by the current mode PWM control system. These operate as PWM (Pulse Width Modulation) mode for heavy load, and it operates as SLLM (Simple Light Load Mode) operation for the light load to improve efficiency. When FPWM is enabled, the SLLM is disabled and these devices operate only the current mode PWM control.

(1) Synchronous rectifier

The application does not require an external Schottky diode as commonly used in conventional DC/DC converter IC's. The low-side power transistor provides two advantages: it reduces the switching losses by careful on-chip timing to prevent shoot-through and improves the leakage current (resulting in large quiescent current) at high operating temperatures.

(2) Current mode PWM control

Synthesizes an additional PWM control signal, representing the inductor current next to the conventional PWM control signal, representing the output voltage of the converter. The current feedback loop is essential to achieve regulation loop stability under all load conditions at so-called continuous condition Buck conversion.

(a) PWM (Pulse Width Modulation) control

The PWM circuit operates as follows: At the start of every switch cycle the oscillator sets the flip-flop that controls the power transistors. This flip-flop is reset again when the slope signal (representing the inductor current) is exceeding the COMP signal (representing the difference between output voltage and internal reference).

(b) SLLM (Simple Light Load Mode) control

For small output currents, this device automatically switches to SLLM. In SLLM, the device operates in PWM control by comparing the output voltage with an internal reference voltage. When the output voltages drops below the reference voltage the output makes several switching pulses in order to raise the output voltage above reference level again. Next, switching pulses are skipped because the SW output is off. Depending on the output load, the controller now waits at very low current consumption until the output voltage is lower than the reference voltage to resume switching. When the time in between the switching pulse skip becomes short the device exits the SLLM mode and resumes normal continuous switching again. The load level of the switching pulse skip is changed by the input voltage and inductor value.

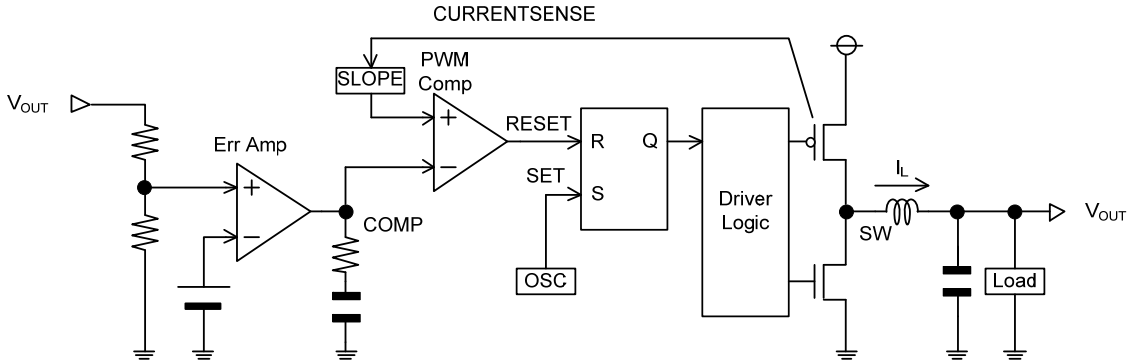


Figure 4. Diagram of current mode PWM control

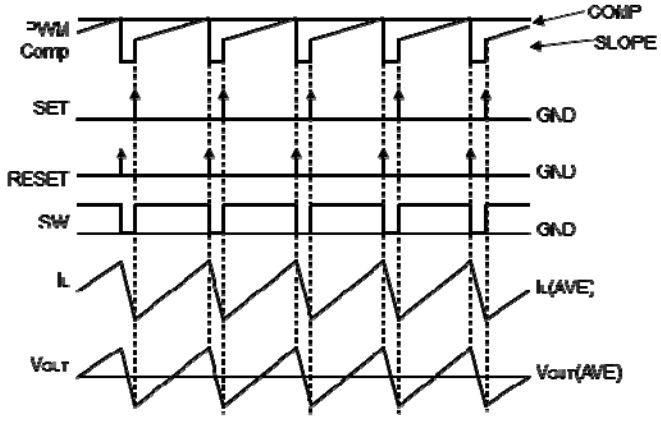


Figure 5. PWM switching timing chart

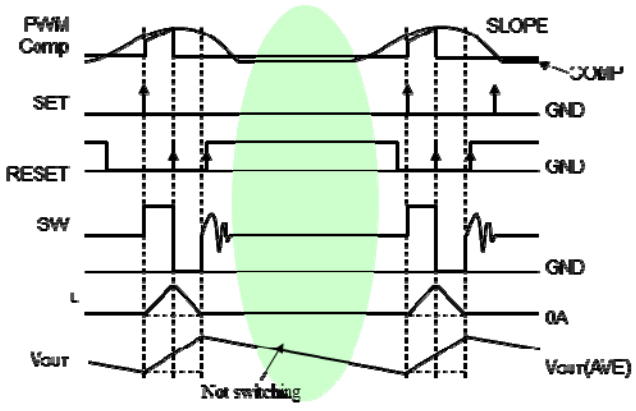


Figure 6. SLLM switching timing chart

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Below the SW and VOUT waveforms during SLLM and PWM are shown.

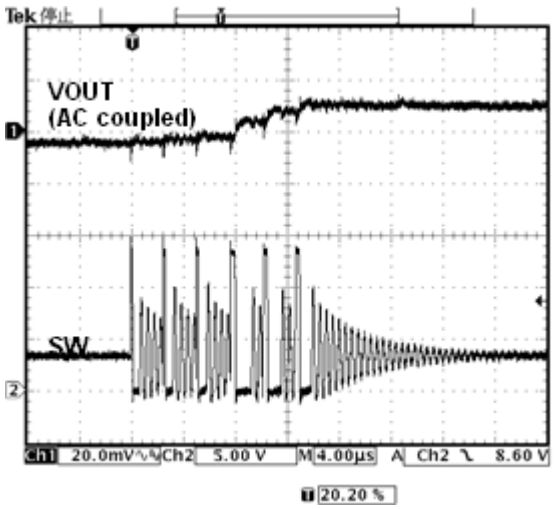


Figure 7. SW and VOUT waveforms at SLLM (Light load)

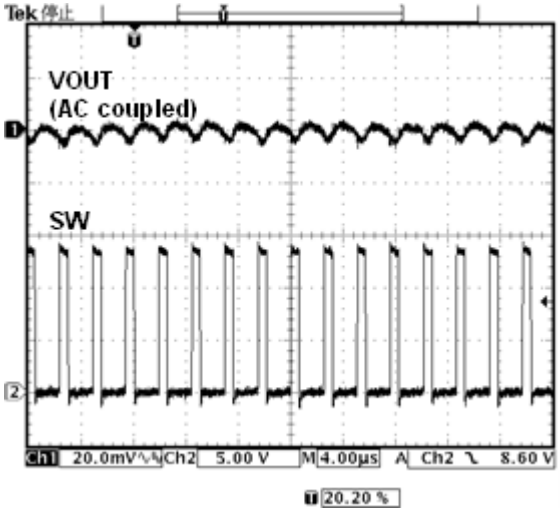


Figure 8. SW and VOUT waveforms at PWM (Heavy load)

Recommended specification for SLLM

The figure below shows the relation between the input / output currents and output ripple voltage at SLLM. SLLM at light load is different from regular PWM and has an increased output ripple voltage. During SLLM, the transient response for heavy loads is also slower. A recommendation is shown below on how to minimize the output ripple voltage and load changes at each of the control modes.

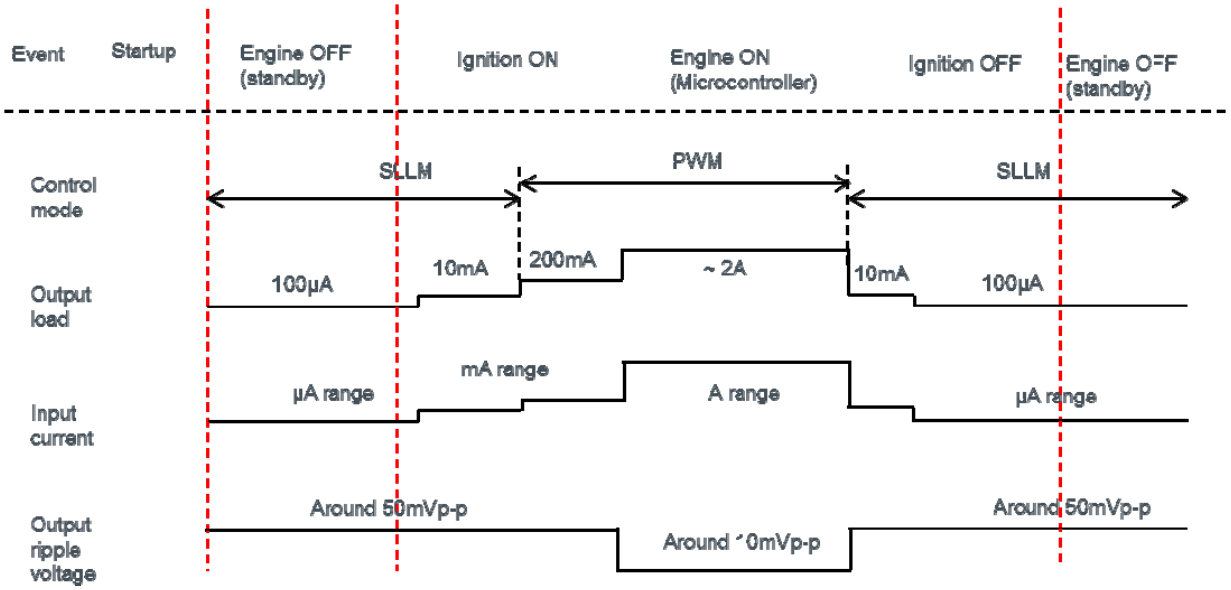


Figure 9. Ripple voltage and load response at SLLM

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Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	PV_{IN},V_{IN}	-0.3 to 42 (1)	V
SW Pin Voltage	V_{SW}	-1.0 to V_{IN}+0.6V	V
VREGB Pin	V_{REGB}	-0.3 to PV_{IN}-6.8V	V
PVIN-VREGB Voltage	PV_{IN} - V_{REGB}	-0.3 to 15	V
EN Pin	V_{EN}	-0.3 to V_{IN}+0.6V	V
RT, COMP, REG, FPWM, REG_L VOUT Pin Voltage	V_{RT}, V_{COMP}, V_{REG}, V_{REG_L}, V_{FPWM}, V_{VOUT}	-0.3 to 7	V
Power Dissipation	P_d	4.00 (2)	W
Storage Temperature Range	T_{stg}	-55 to +150	°C
Maximum Junction Temperature	T_{jmax}	150	°C

(1) Do not however exceed Pd.
(2) Pd derated at 32mW/°C for temperature above Ta=25°C, Mounted on a four layer PCB 70mm×70mm×1.6mm with same size copper area.

Recommended Operating Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V_{IN}	3.6(3) to 35	V
Output Switch Current	I_{SW}	0 to 2(4)	A
Oscillator Frequency	F_{OSC}	200k to 500k	Hz
Operating Temperature Range	T_{opr}	-40 to +105	°C

(3) Initial startup is over 3.9V.
(4) Do not however exceed Pd.

Electrical Characteristics (Unless specified, Ta=-40 to +105°C, VIN=13.2V)

Parameter	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Shut down Current	I_{STB}	-	1	10	μA	V_{EN} =low, Ta=25°C
Quiescent Current1	I_{Q1}	-	22	35	μA	IOUT=0A, Ta=25°C, V_{EN} =high, V_{FPWM} = low (mode: SLLM)
Quiescent Current2	I_{Q2}	-	22	50	μA	IOUT=0A, Ta=-40 to 105°C, V_{EN} =high, V_{FPWM} = low (mode: SLLM)
Circuit Current	I_{CC}	-	1.5	3.0	mA	V_{EN} = high, V_{FPWM} = high, RT=75kΩ, V_{VOUT} = 0V,
REG Voltage	V_{REG}	4.2	4.5	4.6	V	VIN = 5 to 42V
VREGB Voltage	V_{REGB}	PV_{IN} -6.8	PV_{IN} -7.2	PV_{IN} -7.6	V	VREGB=-100μA
Under Voltage Lock Out Threshold	$V_{UVLO-TH1}$	3.30	3.40	3.60	V	VIN Sweep down
Under Voltage Lock Out Hysteresis	$V_{UVLO-HYS}$	80	180	280	mV	

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Electrical Characteristics (Unless specified, Ta=-40 to +105°C, VIN=13.2V)

Output Voltage	BD99010 $V_{OUT,3.3V}$	3.23	3.30	3.37	V	VIN = 6.5 to 18V, PWM mode
		3.17 (5)	3.30 (5)	3.43 (5)	V	VIN = 6.5 to 18V, SLLM Including output ripple (6)
		3.1	3.30	-	V	VIN = 3.6V, I_{Load} = 0 to 1A Ta=25°C
	BD99011 $V_{OUT,5V}$	4.90	5.00	5.10	V	VIN = 6.5 to 18V, PWM mode
		4.80 (5)	5.00 (5)	5.20 (5)	V	VIN = 6.5 to 18V, SLLM Including output ripple (6)
		4.5	4.73	-	V	VIN = 5V, I_{Load} = 0 to 1A Ta=25°C
High Side FET ON resistance	R_{ONH}	-	170	340	mΩ	I_{SW} =-50mA, VIN=13.2V Ta=25°C
	R_{ONH_LV}	-	265	500	mΩ	I_{SW} =-50mA, VIN=3.6V Ta=25°C
Low Side FET ON resistance	R_{ONL}	-	130	260	mΩ	I_{SW} =50mA, VIN=13.2V Ta=25°C
SW Leakage Current	I_{OLEAK}	-	-	10	μA	VIN = 42V, V_{SW} = 0V, V_{EN} =low, Ta=25°C
DC Output Current Limit	I_{OLIMIT}	2.4 (5)	3.3 (5)	4.2 (5)	A	
Oscillator Frequency	F_{OSC}	320	400	480	kHz	RT=75kΩ, V_{IN}= 6.5 to 18V
Soft Start Time	T_{SS}	3	6	11	ms	
Enable						
EN Threshold	V_{IH-EN}	2.0	-	-	V	
	V_{IL-EN}	-	-	0.8	V	
EN Hysteresis	V_{EN-HYS}	50	100	200	mV	
EN Sink Current	I_{EN}	-	0.1	1.0	μA	V_{EN} =5V, Ta=25°C
Forced PWM mode						
FPWM Threshold	V_{IH-PWM}	2.0	-	-	V	PWM mode
	V_{IL-PWM}	-	-	0.8	V	
FPWM Hysteresis	$V_{FPWM-HYS}$	200	330	460	mV	
FPWM Sink Current	I_{FPWM}	4.0	7.5	12.0	μA	V_{FPWM} =5V

(5) Not production tested. Guaranteed by design.
(6) Using external components on page 17 and 18.

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Typical Performance Curves

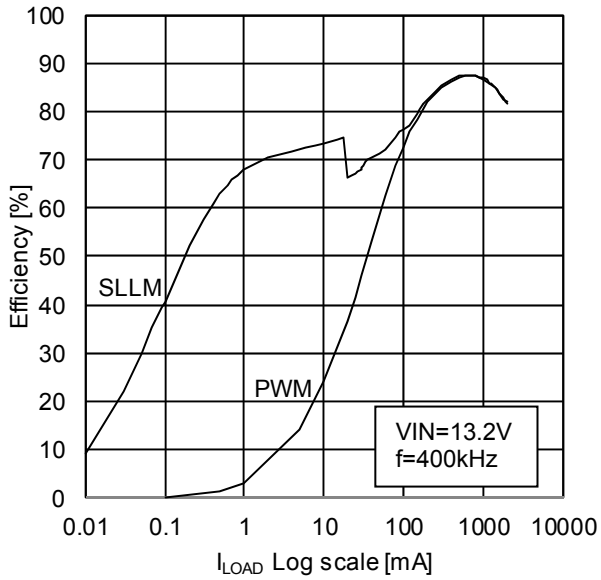


Figure 10. Efficiency Log Scale
(BD99010EFV-M : VOUT.3.3V)

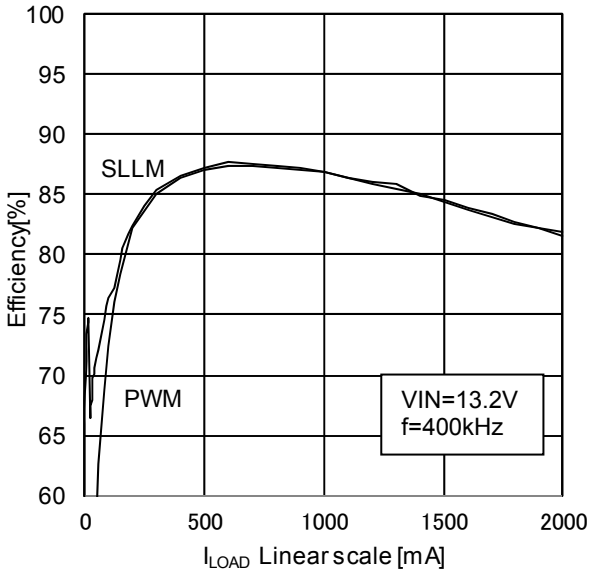


Figure 11. Efficiency Linear Scale
(BD99010EFV-M : VOUT.3.3V)

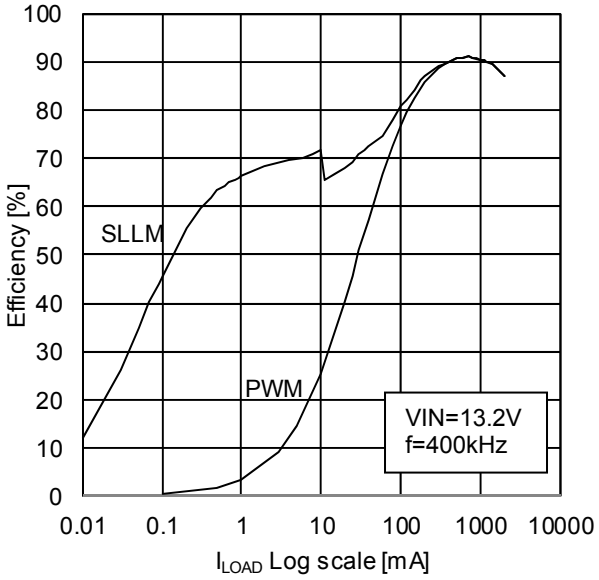


Figure 12. Efficiency Log Scale
(BD99011EFV-M : VOUT.5V)

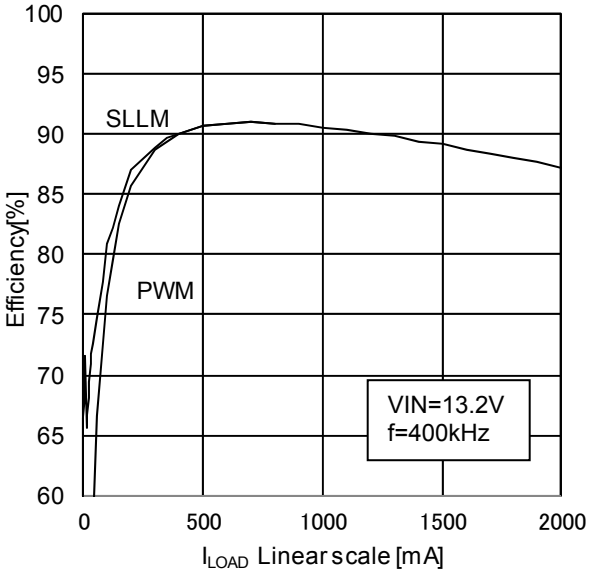


Figure 13. Efficiency Linear Scale
(BD99011EFV-M: VOUT.5V)

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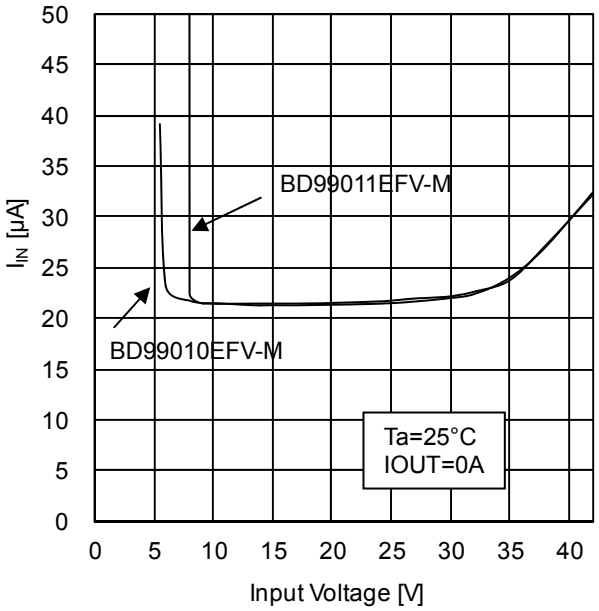


Figure 14. I_{IN} vs. Input Voltage at No Load

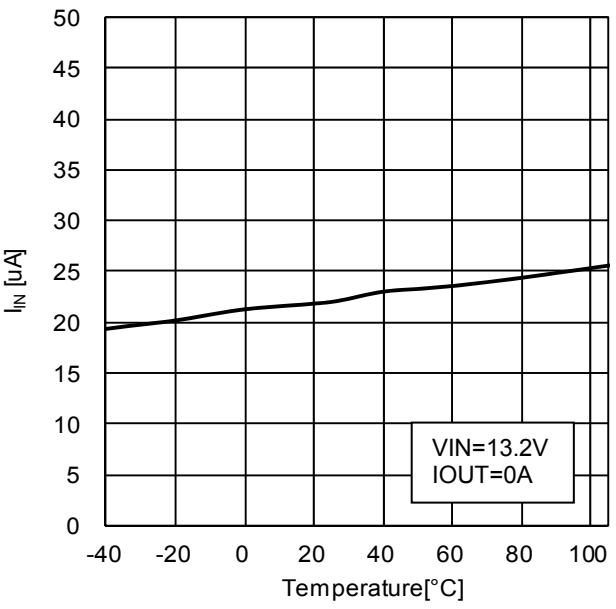


Figure 15. I_{IN} vs. Temperature at No Load

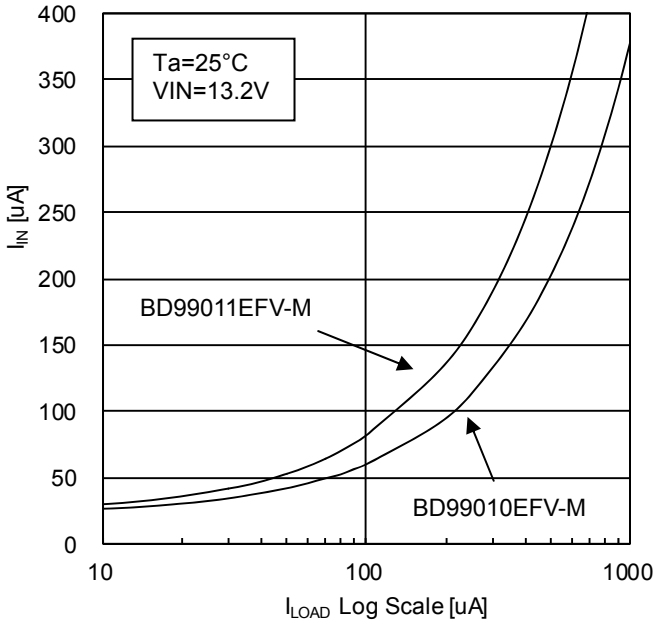


Figure 16. I_{IN} vs. I_{LOAD}

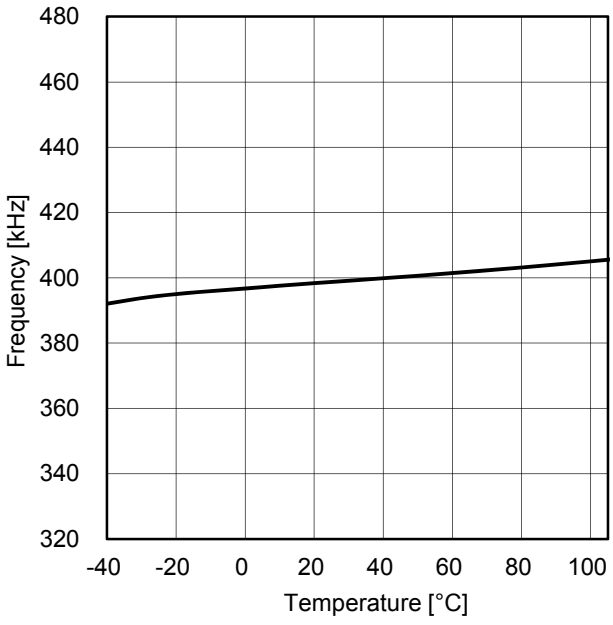


Figure 17. Frequency vs. Temperature

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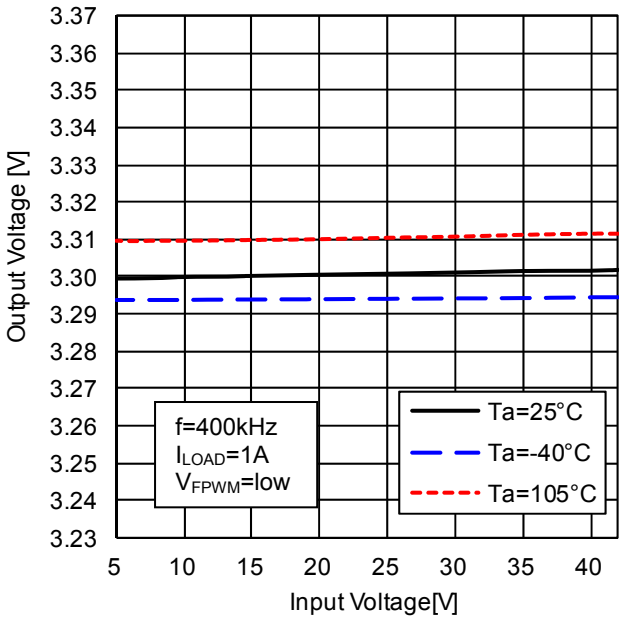


Figure 18. Line Regulation 1
(BD99010EFV-M: VOUT.3.3V)

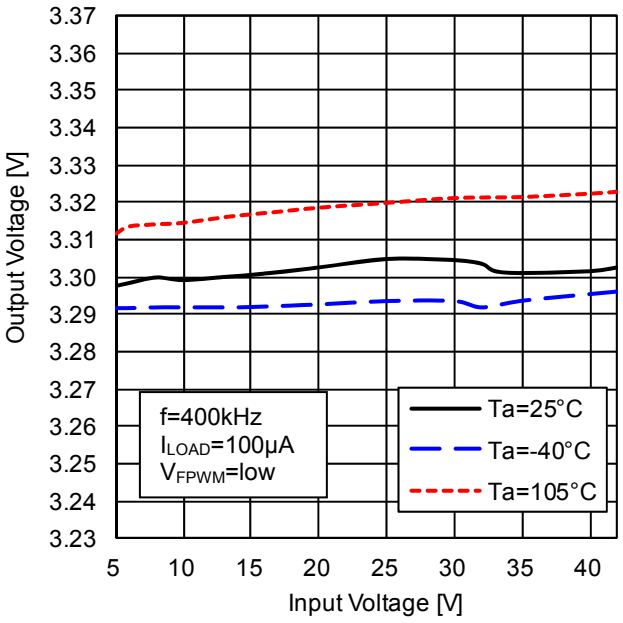


Figure 19. Line Regulation 2
(BD99010EFV-M: VOUT.3.3V)

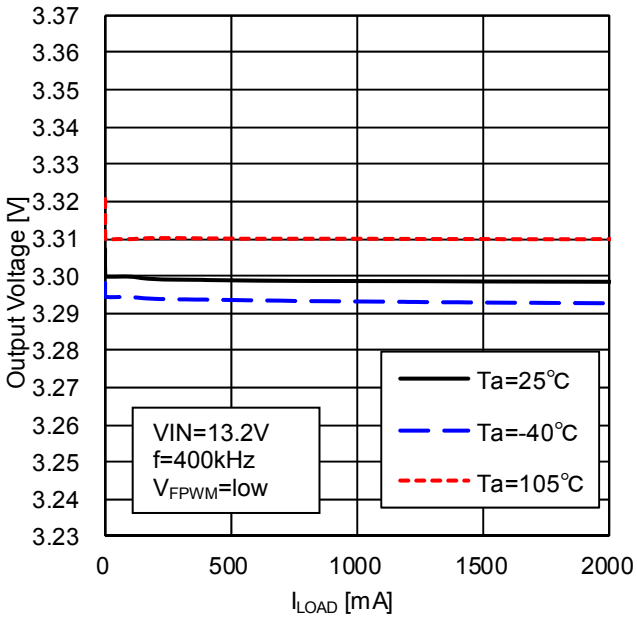


Figure 20. Load Regulation
(BD99010EFV-M: VOUT.3.3V)

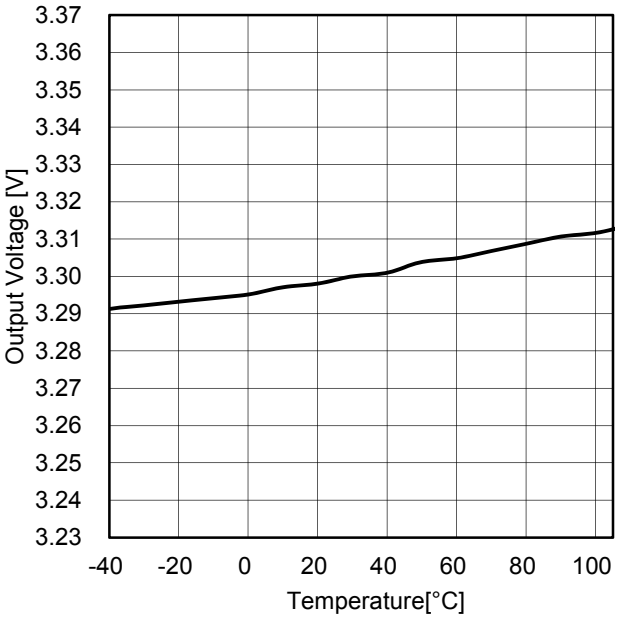


Figure 21. Output Voltage vs. Temperature
(BD99010EFV-M: VOUT.3.3V)

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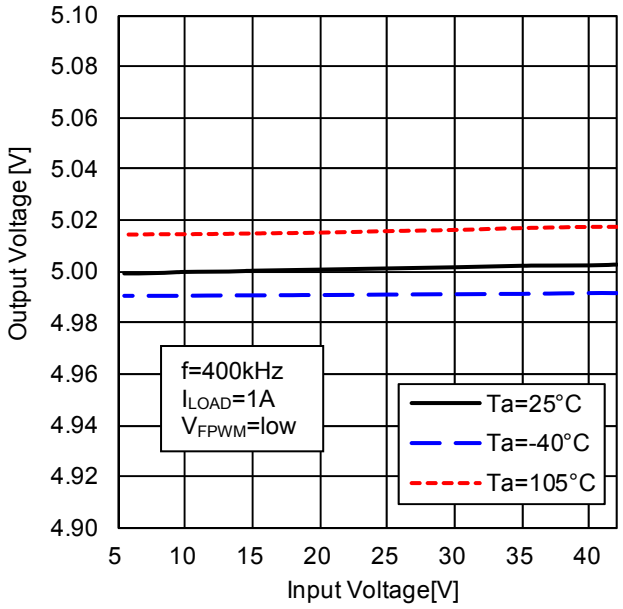


Figure 22. Line Regulation 1
(BD99011EFV-M: VOUT.5V)

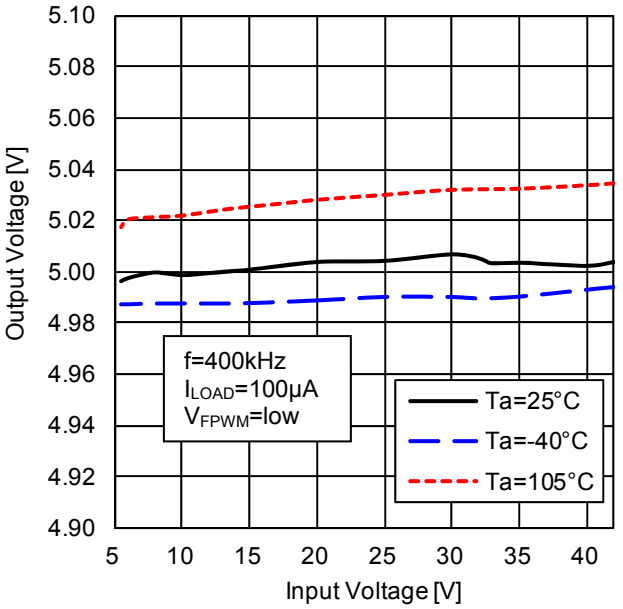


Figure 23. Line Regulation 2
(BD99011EFV-M: VOUT.5V)

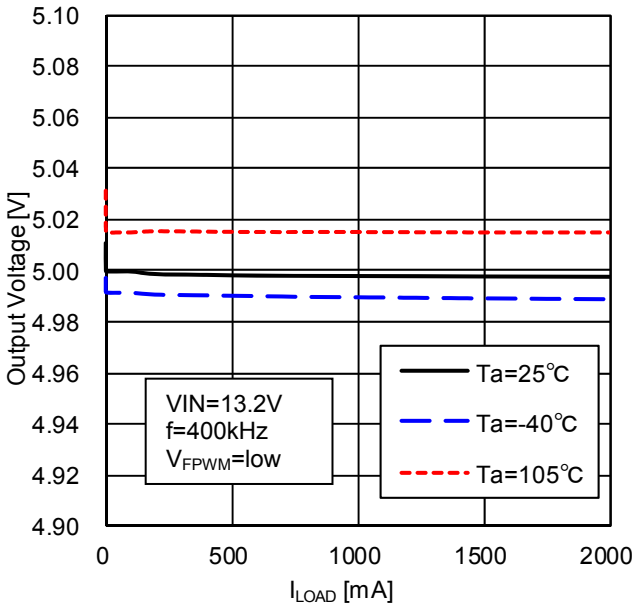


Figure 24. Load Regulation
(BD99011EFV-M: VOUT.5V)

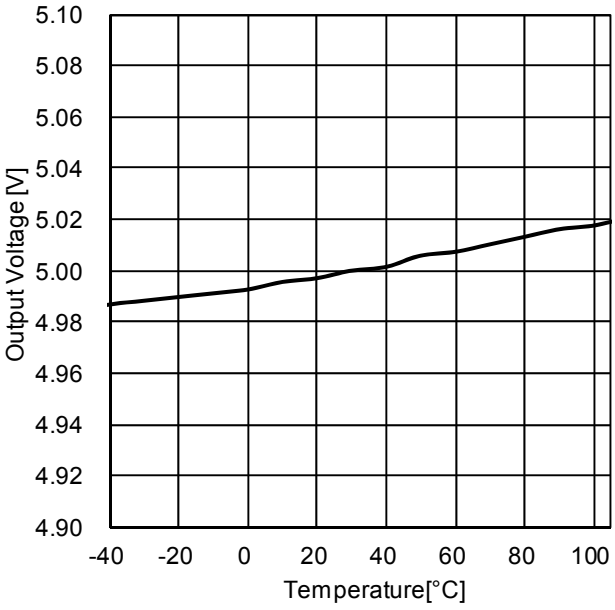


Figure 25. Output Voltage vs. Temperature
(BD99011EFV-M: VOUT.5V)

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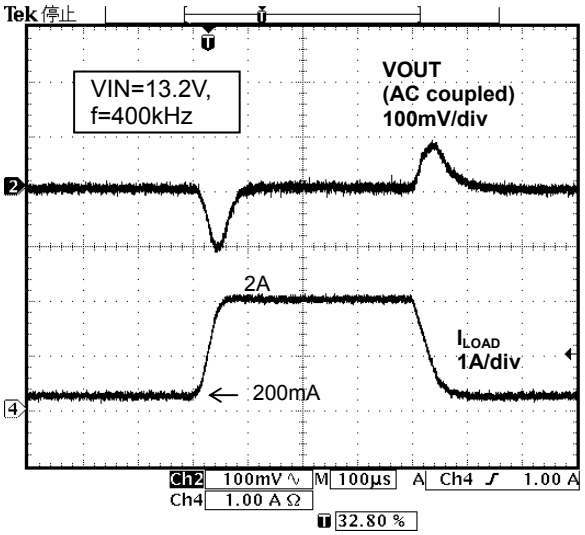


Figure 26. Transient Response
(BD99010EFV-M: VOUT.3.3V)

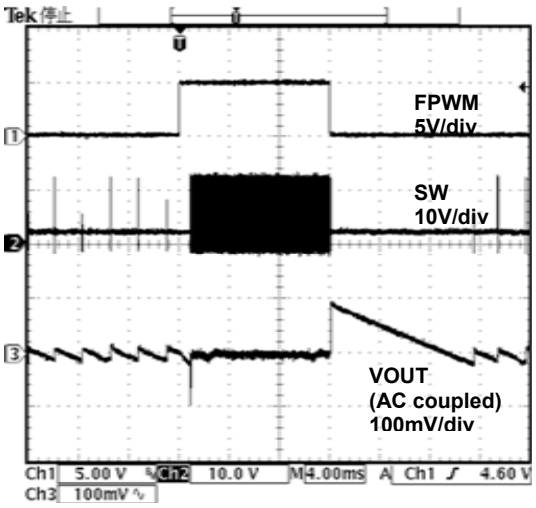


Figure 27. Mode Transition (SLLM ⇔ FWPM)
(BD99010EFV=M: VOUT.3.3V)

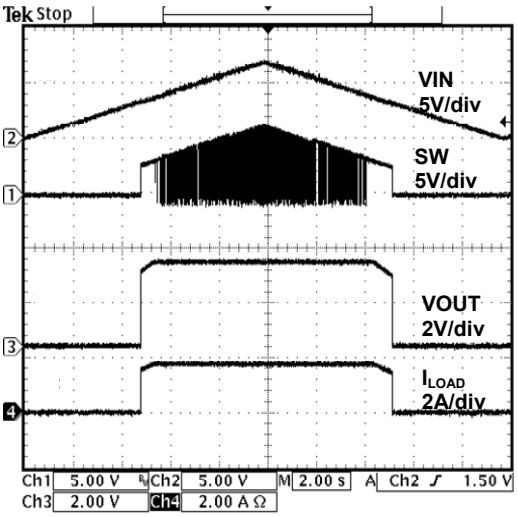


Figure 28. Slow Input Ramp Up and Down
(BD99010EFV-M: VOUT.3.3V)

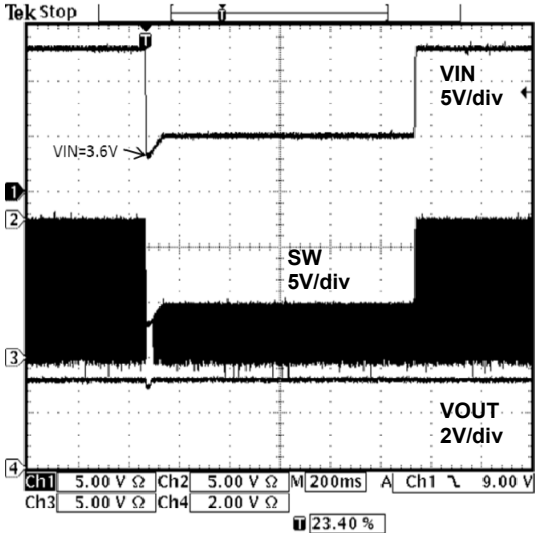


Figure 29. VIN Cranking
(BD99010EFV-M: VOUT.3.3V)

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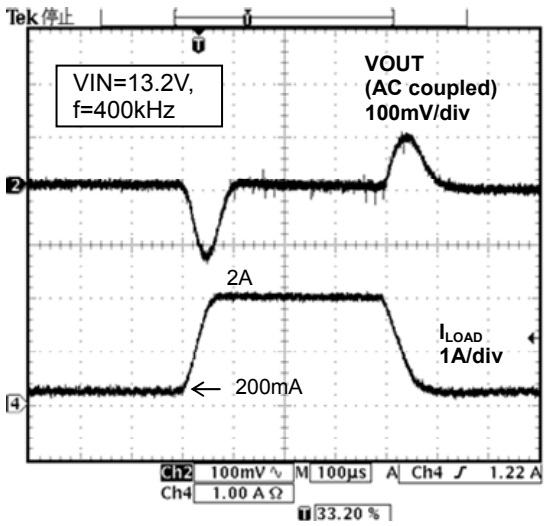


Figure 30. Transient Response
(BD99011EFV-M: VOUT.5V)

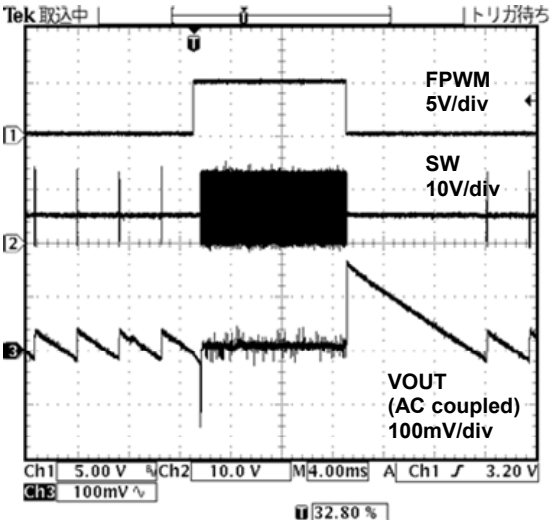


Figure 31. Mode Transition (SLLM ⇔ FWPM)
(BD99011EFV-M: VOUT.5V)

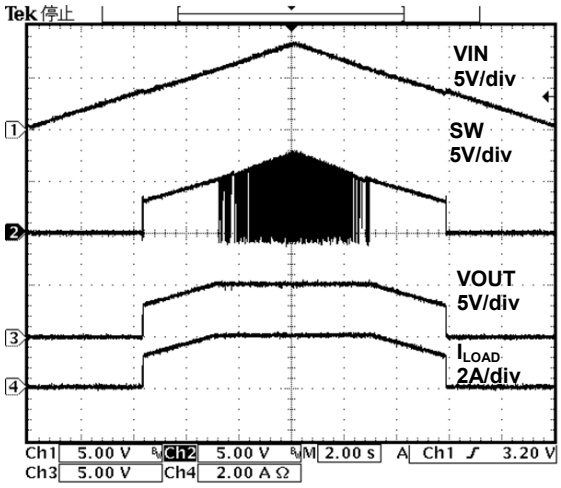


Figure 32. Slow Input Ramp Up and Down
(BD99011EFV-M: VOUT.5V)

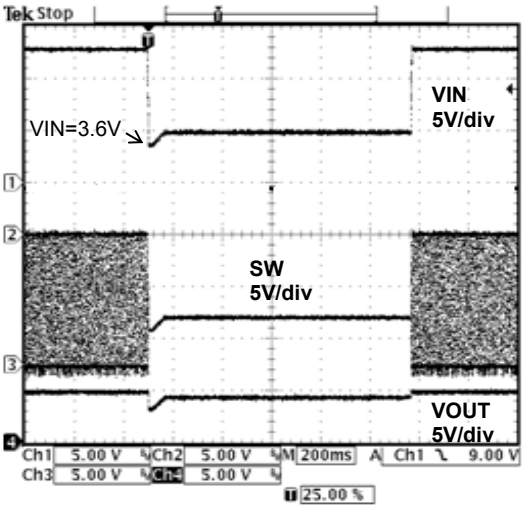


Figure 33. VIN Cranking
(BD99011EFV-M: VOUT.5V)

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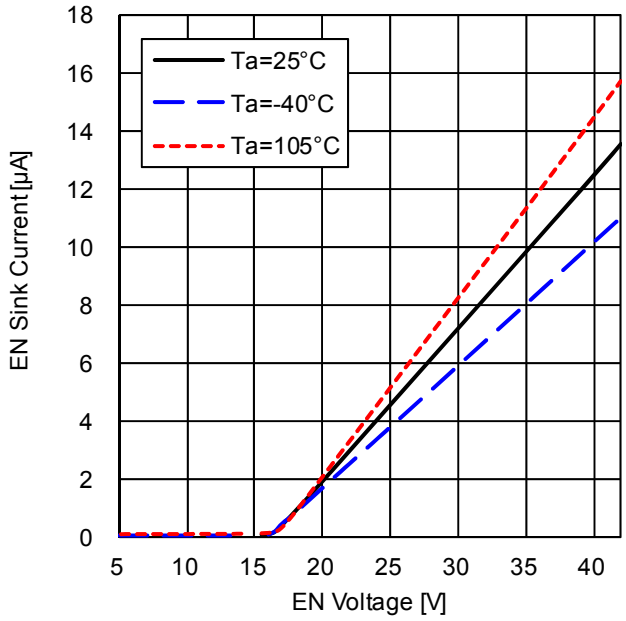


Figure 34. EN Sink Current

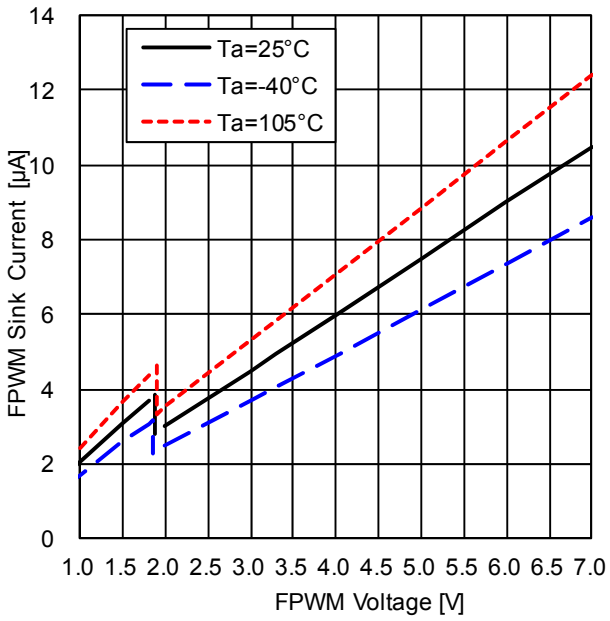


Figure 35. FPWM Sink Current

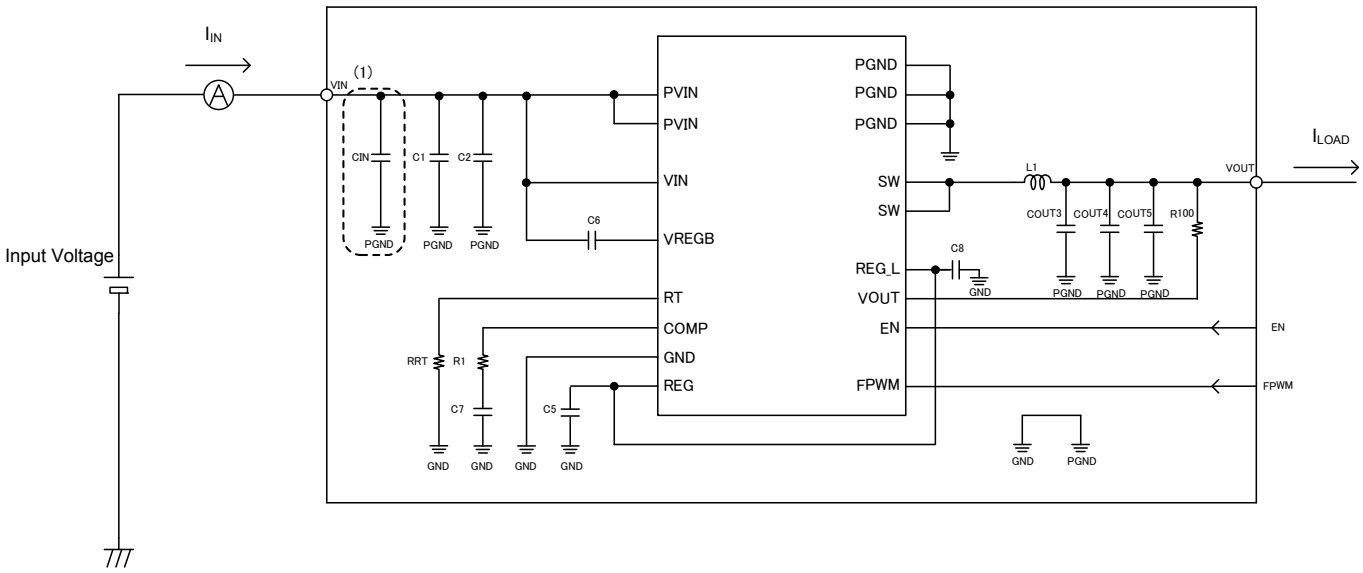


Figure 36. Measurement Figure

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Timing Chart

(1) Startup operations

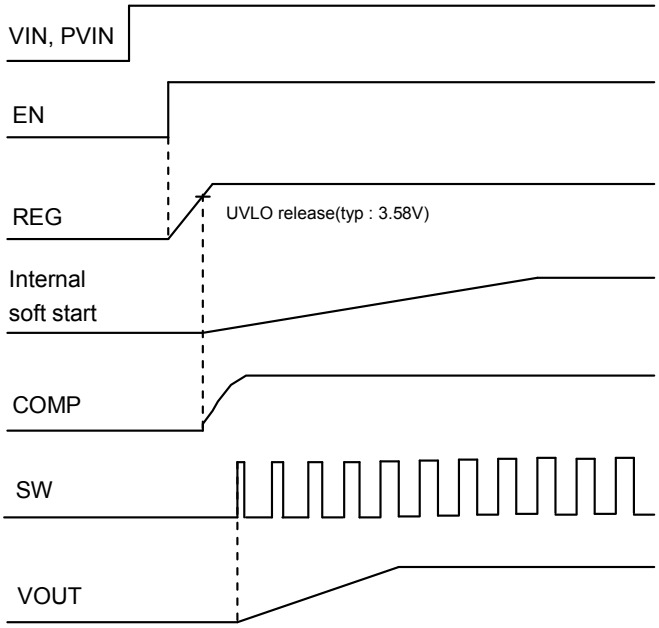


Figure 37. Timing Chart 1 (Start up operation)

(2) Protection operations (VIN,PVIN=13.2V, V_{EN}=high)

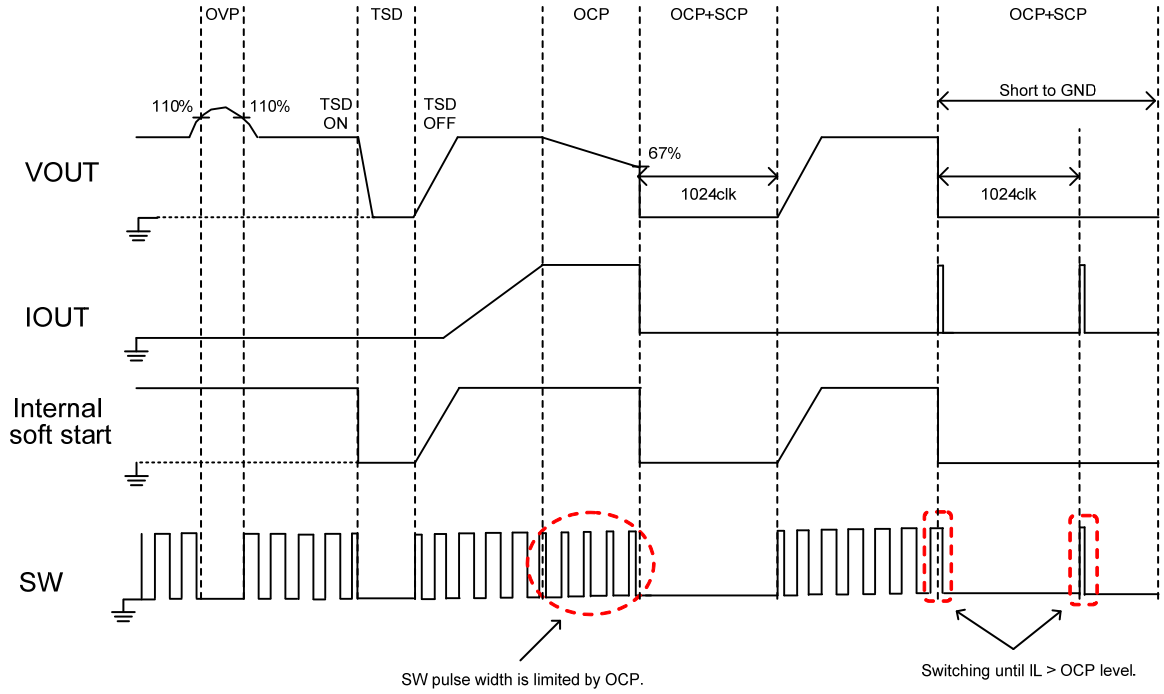


Figure 38. Timing Chart 2 (Protection operation)

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Applications

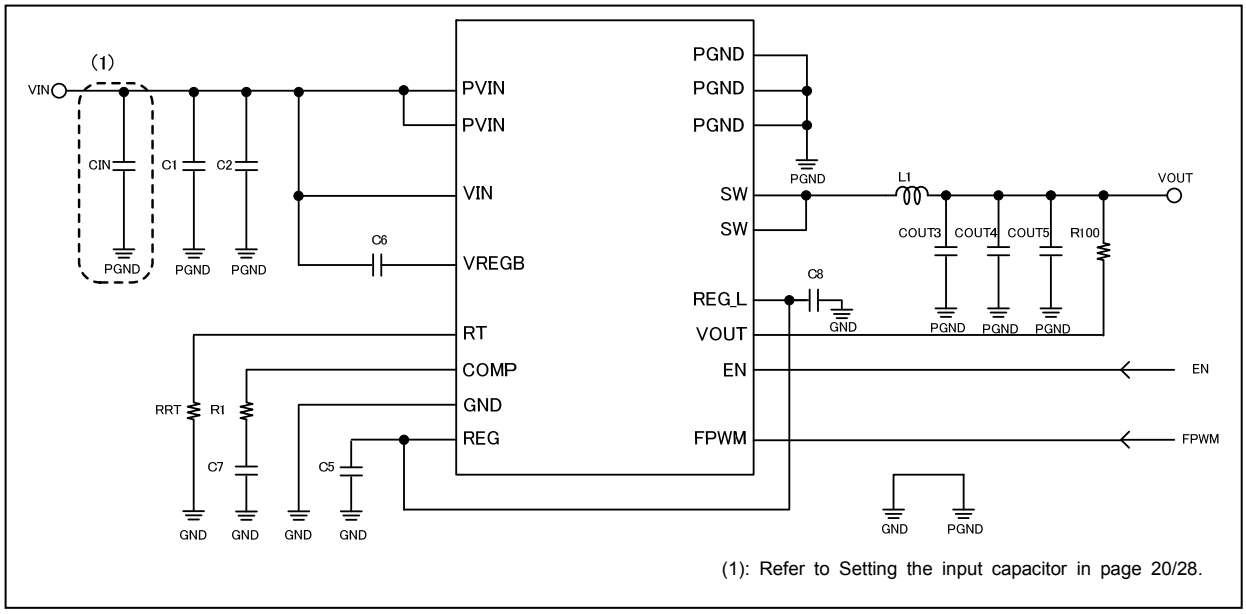


Figure 39. Application circuit

BD99010EFV-M

No	Component Name	Component Value	Description	Product Name	Comment
1	CIN(1)	220µF	Capacitor, 50V, electrolytic	-	
2	C1	4.7µF	Capacitor, 50V, ceramic	GCM32ER71H475KA55	
3	C2	-	Capacitor, 50V, ceramic	-	
4	COUT3	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
5	COUT4	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
6	COUT5	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
7	C5	1µF	Capacitor, 16V, ceramic	GCM188R71C105KA64	
8	C6	0.1µF	Capacitor, 50V, ceramic	GCM188R71H104KA57	
9	C7	2200pF	Capacitor, 50V, ceramic	GCM188R71H222KA37	f=200kHz
		1500pF	Capacitor, 50V, ceramic	GCM188R71H152KA37	f=300kHz
		1000pF	Capacitor, 50V, ceramic	GCM188R71H102KA37	f=400kHz
		1000pF	Capacitor, 50V, ceramic	GCM188R71H102KA37	f=500kHz
10	C8	-	Capacitor, 16V, ceramic	-	
11	R1	27kΩ	Resistor,	MCR03EZP Series	f=200kHz
		27kΩ	Resistor,	MCR03EZP Series	f=300kHz
		33kΩ	Resistor,	MCR03EZP Series	f=400kHz
		33kΩ	Resistor,	MCR03EZP Series	f=500kHz
12	RRT	164kΩ	Resistor,	MCR03EZP Series	f=200kHz
		104kΩ	Resistor,	MCR03EZP Series	f=300kHz
		75kΩ	Resistor,	MCR03EZP Series	f=400kHz
		58kΩ	Resistor,	MCR03EZP Series	f=500kHz
13	R100	0Ω	Resistor,	MCR03EZP Series	
14	L1	22µH	Inductor	CLF10040T-220M-H	f=200kHz
		15µH	Inductor	CLF10040T-150M-H	f=300kHz
		10µH	Inductor	CLF10040T-100M-H	f=400kHz
		10µH	Inductor	CLF10040T-100M-H	f=500kHz

(1): Refer to Setting the input capacitor in page 20/28.

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BD99011EFV-M

No	Component Name	Component Value	Description	Product Name	Comment
1	CIN(1)	220µF	Capacitor, 50V, electrolytic	-	
2	C1	4.7µF	Capacitor, 50V, ceramic	GCM32ER71H475KA55	
3	C2	-	Capacitor, 50V, ceramic	-	
4	COUT3	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
5	COUT4	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
6	COUT5	22µF	Capacitor, 10V, ceramic	GCM32ER71A226KE12	
7	C5	1µF	Capacitor, 16V, ceramic	GCM188R71C105KA64	
8	C6	0.1µF	Capacitor, 50V, ceramic	GCM188R71H104KA57	
9	C7	2200pF	Capacitor, 50V, ceramic	GCM188R71H222KA37	f=200kHz
		1500pF	Capacitor, 50V, ceramic	GCM188R71H152KA37	f=300kHz
		1000pF	Capacitor, 50V, ceramic	GCM188R71H102KA37	f=400kHz
		1000pF	Capacitor, 50V, ceramic	GCM188R71H102KA37	f=500kHz
10	C8	-	Capacitor, 16V, ceramic	-	
11	R1	20kΩ	Resistor,	MCR03EZP Series	f=200kHz
		20kΩ	Resistor,	MCR03EZP Series	f=300kHz
		20kΩ	Resistor,	MCR03EZP Series	f=400kHz
		20kΩ	Resistor,	MCR03EZP Series	f=500kHz
12	RRT	164kΩ	Resistor,	MCR03EZP Series	f=200kHz
		104kΩ	Resistor,	MCR03EZP Series	f=300kHz
		75kΩ	Resistor,	MCR03EZP Series	f=400kHz
		58kΩ	Resistor,	MCR03EZP Series	f=500kHz
13	R100	0Ω	Resistor,	MCR03EZP Series	
14	L1	22µH	Inductor	CLF10040T-220M-H	f=200kHz
		15µH	Inductor	CLF10040T-150M-H	f=300kHz
		10µH	Inductor	CLF10040T-100M-H	f=400kHz
		10µH	Inductor	CLF10040T-100M-H	f=500kHz

(1): Refer to Setting the input capacitor in page 20/28.

These are the reference value. These characteristics are influenced by the PCB layout pattern, used parts, etc. verification and confirmation with the actual application is recommended.

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Selection of External Components

(1) Setting the Inductor (L) value

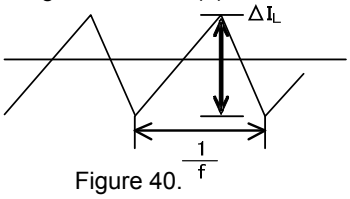


Figure 40.

The inductor-value determines the output current ripple. As shown in the following equation, the larger the inductor, and the higher the switching frequency, the lower the ripple current.

$$\Delta I_L = \frac{(VIN-VOUT)\times VOUT}{L\times VIN\times f} \quad [A]$$

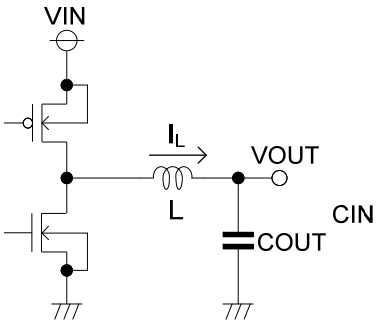


Figure 41.

The optimal output current ripple setting is ca. 30% of the maximum current.

$$\Delta I_L = 0.3\times I_{LOADmax} \quad [A]$$

$$L = \frac{(VIN-VOUT)\times VOUT}{\Delta I_L\times VIN\times f} \quad [H]$$

(ΔIL: output current ripple, f: switching frequency)

Care should be taken not to exceed the maximum current rating of the inductor since this will lead to magnetic saturation and consequently to loss of efficiency. It is recommended to allow for sufficient margin to ensure that the peak current does not exceed the coil current rating. Use low resistance (DCR, ACR) coils to minimize coil loss and increase efficiency.

(2) Setting the output capacitor COUT value

Select the output capacitor with consideration to the acceptable ripple voltage (VP-P) at high output current conditions. The following equation is used to determine the output ripple voltage.

$$\Delta V_{PP} = \Delta I_L \times R_{ESR} + \frac{\Delta I_L}{2XCOUT} \times \frac{VOUT}{VIN} \times \frac{1}{f} \quad [V]$$

in which: f denotes the switching frequency

The output COUT setting needs to be kept within the allowable ripple voltage range.
The above formula gives an indication of the ripple voltage and sufficient margin should be taken to accommodate for aging and component variations. Low ESR capacitors enable a lower output ripple voltage. Also, the value of the buffer capacitor should not be taken too large in order to meet the requirement for output startup time within the soft start time range. As an estimate for the maximum value of COUT the following estimation can be taken:

$$COUT \leqq \frac{T_{SS}\times(I_{LIMIT}-I_{LOAD})}{VOUT}$$

T_{SS}: Soft start time
I_{LIMIT}: Output current limit value

Note: non-optimal capacitance values may cause startup problems. Especially in cases of extremely large capacitance values, the possibility exists that the inrush current at startup will activate the overcurrent protection, thus slowing down the output voltage startup. At even more extreme values, one faces the risk of falsely triggering the SCP (short circuit protection) causing the output voltage not to start up at all. Therefore, validation and conformation with the actual application is recommended.

Also at low load conditions the output buffer capacitor is determining the output voltage ripple but via a different mechanism. The BD9901xEFV-M makes a small series of switching cycles which charges the buffer capacitor following a staircase shape curve. Consecutively, the switching is paused until the buffer capacitor is discharged according to a linear shape curve again to the reference level. Generally, this leads to a somewhat larger voltage ripple as in higher load conditions.

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(3) Setting input capacitor

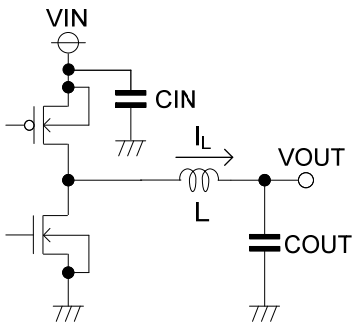


Figure 42.

The input capacitor acts as (i) Decoupling capacitor (ii) Bulk capacitor.
Decoupling capacitor: Ceramic capacitor of value 4.7µF to 10µF is necessary. The voltage rating should be > 1.2x max input voltage or > 2 x normal input voltage. It is better to place it as close as possible to PVIN pin and PGND pin.
Bulk capacitor: It acts as a backup power supply and tries to keep the input potential when the input power supply drops. The low ESR electrolytic capacitor with large capacity is suitable for the bulk capacitor. Based on application appropriate value can be taken. When the impedance on the input side is high (long wiring from the power supply to VIN, etc.), the high capacity is needed
In application, it is necessary to verify that there is no problem at output due to the decrease of VIN at transient response. Please be careful not to exceed the rated ripple current of the capacitor.
The I_{RMS} value of the input ripple current can be calculated with the expression below.

$$I_{RMS} = I_{LOAD} \times \frac{\sqrt{VOUT \times (VIN-VOUT)}}{VIN} [A]$$

In addition, in the automotive and other applications requiring high reliability, it is recommended that the multiple electrolytic capacitors are connected in parallel to avoid a dry up. In order to reduce a risk of destruction because of short in a ceramic capacitor, we recommend using 2 serials +2 parallel structure.
Since the lineup also of what packed 2 series and 2 parallel structure in 1package, respectively is carried out by each capacitor supplier, please confirm to each supplier.

(4) Setting the switching frequency

The switching frequency is set with the resistor RT.
The setting range is 200kHz to 500kHz.The relation between the resistance value and the oscillation frequency is shown in the table below. Selecting a resistor outside the range shown below may cause malfunctions of the switching regulator.

RT resistance	Oscillation frequency
164 kΩ	200kHz
128 kΩ	250kHz
104 kΩ	300kHz
88 kΩ	350kHz
75 kΩ	400kHz
66 kΩ	450kHz
58 kΩ	500kHz

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(5) Setting the phase compensation circuit

The phase compensation circuitry provides regulation loop stability and ensures sufficient regulation bandwidth for rapid load and supply voltage step responses. There are two conditions to avoid (near) negative feedback that causes regulation in stability:

(a) At the frequency of unity loop gain(0dB), fc. the phase delay should be 150° or less. (i.e. the so-called phase margin is 30° or higher)

(b) As the DC/DC converter application is sampled according to the switching frequency, fc should be set to 1/10 or less of the switching frequency.

In order to achieve sufficient rapid step response fc should be as high as possible and consequently the switching frequency has to be set as high as possible.

The phase compensation is set by the capacitors and resistors serially connected to the COMP pin. Achieving stability by using the phase compensation is done by cancelling the 2 poles (error amp pole denoted as fp1 and power stage pole denoted as fp2) of the regulation loop by means of a zero, denoted as fz1, of the capacitor C3 in the phase compensation circuit.

fp1, fp2 and fz1 are determined by the formulas below.

$$fp1 = \frac{g_m}{2\pi \times C_3 \times A_V}$$

$$fp2 = \frac{1}{2\pi \times COUT \times R_{LOAD}}$$

$$fz1 = \frac{1}{2\pi \times C_3 \times R_1}$$

In the formula above, g_m is the error amp Trans conductance (140 µA/V) and A_V is the error amp voltage gain (2500 V/V)

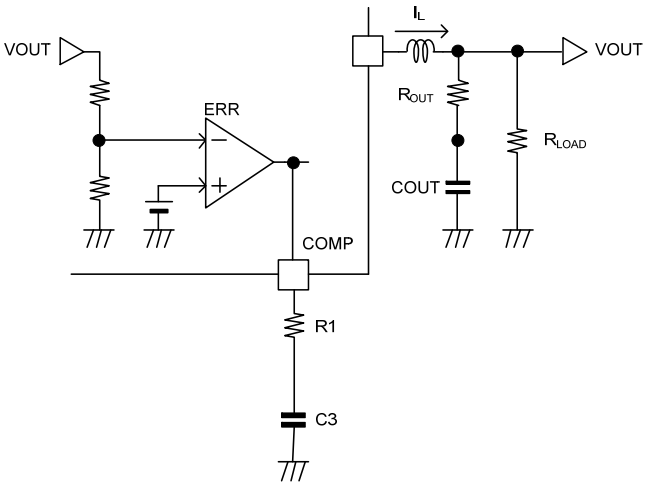


Figure 43.

During startup in forced PWM mode at light loads the duty cycle of the regulator has to be very small and the regulation loop has a tendency to become marginally instable causing a large voltage ripple or noise. This noise during startup can be prevented by creating another zero, fz2, in the regulation loop with resistor R_{OUT}.

$$fz2 = \frac{1}{2\pi \times COUT \times R_{OUT}}$$

Please note that adding this resistor is effectively increasing the ESR of the output buffer capacitor and hence increasing the ripple voltage according eq. 2. In practice a small value suffices to remove all noise during soft start while keeping a small ripple voltage of ca. 50mV_{P-P} at high load situations. In case, the noise at low voltages during startup is not negatively affecting other system components the resistor R_{OUT} can be omitted. Moreover, in case of the start-up at SLLM with light load, the ripple voltage does not become large during the soft start.

This setting is obtained by using a simplified calculation, therefore, small adjustments in values in the actual application may be required. Also as these characteristics are influenced by the substrate layout, load conditions, etc. validation and confirmation with the actual application at time of mass production design is recommended.

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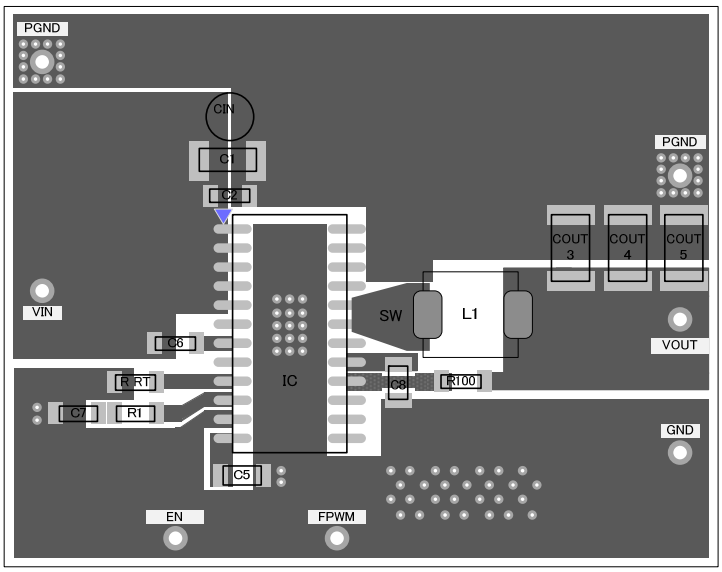
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PCB Layout Pattern

The PCB layout greatly influences the stable operation of the IC. Depending on the PCB layout IC might not show its original characteristics or might not function properly.
Please note the following points when creation the PCB layout. Moreover, Fig 35 shows the recommended layout pattern and component placement.

- The input capacitors C1, C2 and CIN should be placed as close as possible to the VIN, PVIN GND and PGND. Especially, C1 and C2 should be placed as close as possible to PVIN and PGND pin.
- The output voltage feedback line VOUT should be separated from lines with a lot of noise such as the SW line.
- The output capacitors COUT3, COUT4 and COUT5 should be placed in close proximity to inductor L1.
- The inductor L1 should be placed as close as close as possible to the SW pin. The pattern area of the SW node should be as small as possible.
- EN pin has to be connected GND or supplied with the voltage below 0.8V to set the device in shut down mode because the EN pin is not pulled-down internally.
- The exposed die pad on the bottom of the package has to be soldered to GND. Then the device is connected to GND electrically and gets good thermal performance.
- The feedback frequency characteristics (phase margin) can be measured by inserting a resistor at the location of R100 and using FRA. However, this should be shorted during normal operation.

<TOP VIEW>



<BOTTOM VIEW>

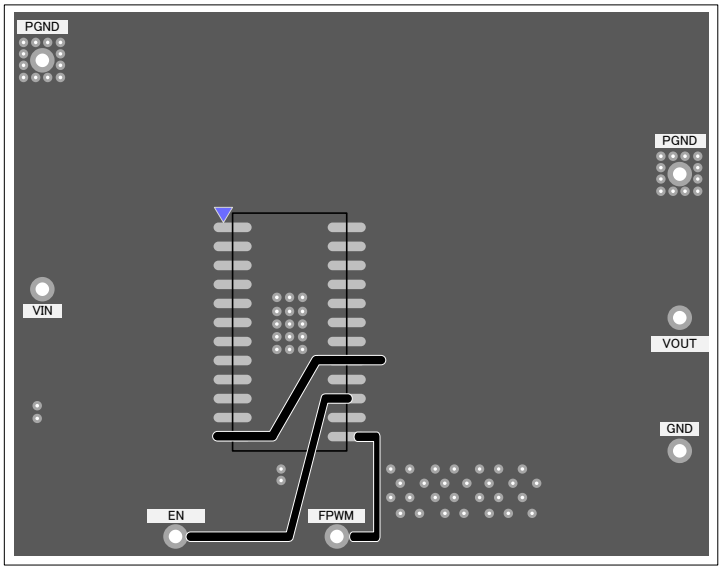


Figure 44. Reference layout pattern

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Heat Dissipation

The allowance maximum junction temperature Tj of BD99010EFV-M and BD99011EFV-M is 150℃. When the junction temperature becomes 150℃ or more, the thermal shutdown circuit operates, and the device becomes shut down. Therefore, it is necessary to design the system requirements and the board layout so that the junction temperature should not exceed 150℃ in the power-supply voltage, the output load, and the operating temperature rating.

The maximum junction temperature can be determined from ambient temperature Ta, thermal resistance θja of package and heat dissipation P of IC by the following equation.

$$Tj = Ta + \theta ja \times P\ [℃]$$

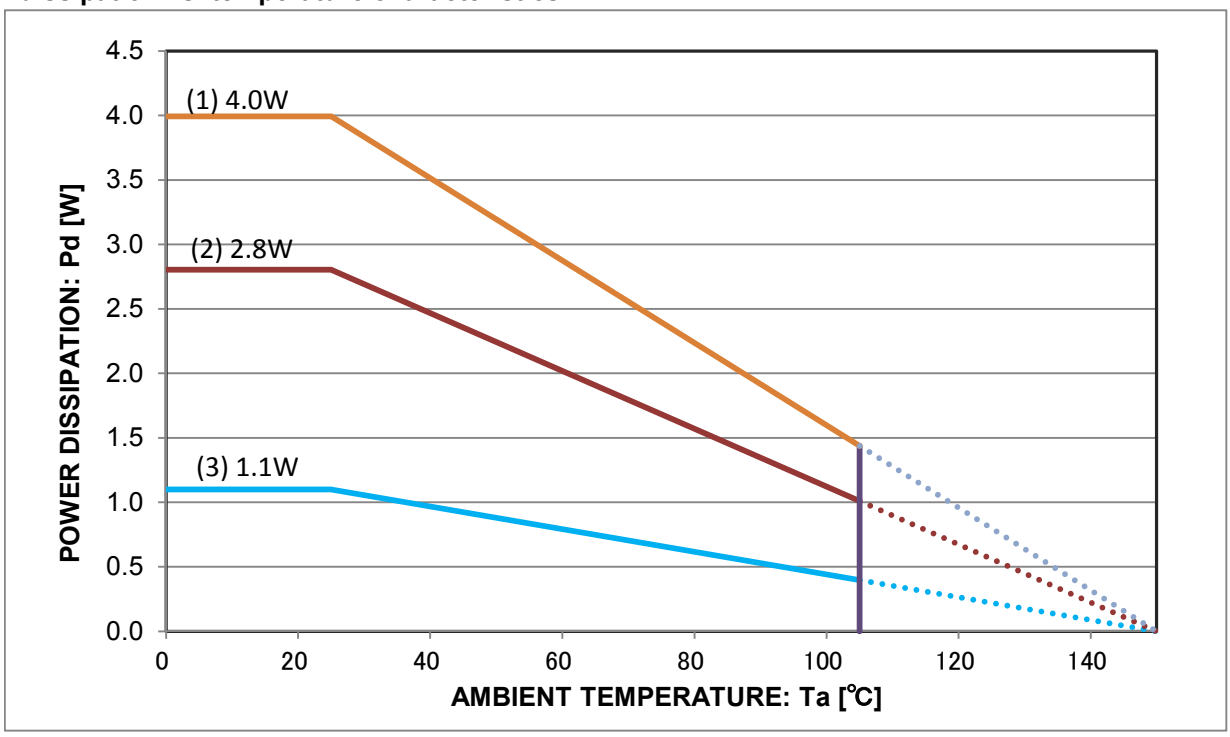
Thermal resistance θja of the package changes depending on the number of layers and the area of the copper foil of the board etc.

Heat dissipation PTOTAL of IC can be calculated by the next expression.

PTOTAL = PICC + PRON + PSW [W]
PICC = VIN × ICC ・・・ Heat dissipation in control circuit
PRON = Ron × IOUT2 ・・・ Heat dissipation in output FET
Ron = D × RONH + (1 - D) × RONL
PSW = Tr × IOUT × VIN × Fosc ・・・ Heat dissipation in switching

ICC : Circuit current (refer to page. 6)
RONL : ON resistance of L-side FET (refer to page. 7)
D : ON duty (=VOUT/ VIN) IOUT : Output load current
RONH : ON resistance of H-side FET (refer to page. 7)
Fosc : Oscillator frequency
Tr : switching rise and fall time (approximately 20ns)

Power dissipation vs. temperature characteristics



(1) : Standalone IC
(2) : Mounted on a ROHM 2 layer standard board
（70mm×70mm×1.6mm glass-epoxy board）
(3) : Mounted on a ROHM 4 layer standard board
（70mm×70mm×1.6mm glass-epoxy board）

Figure 45. Power dissipation vs. temperature characteristics

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I/O Equivalence Circuits

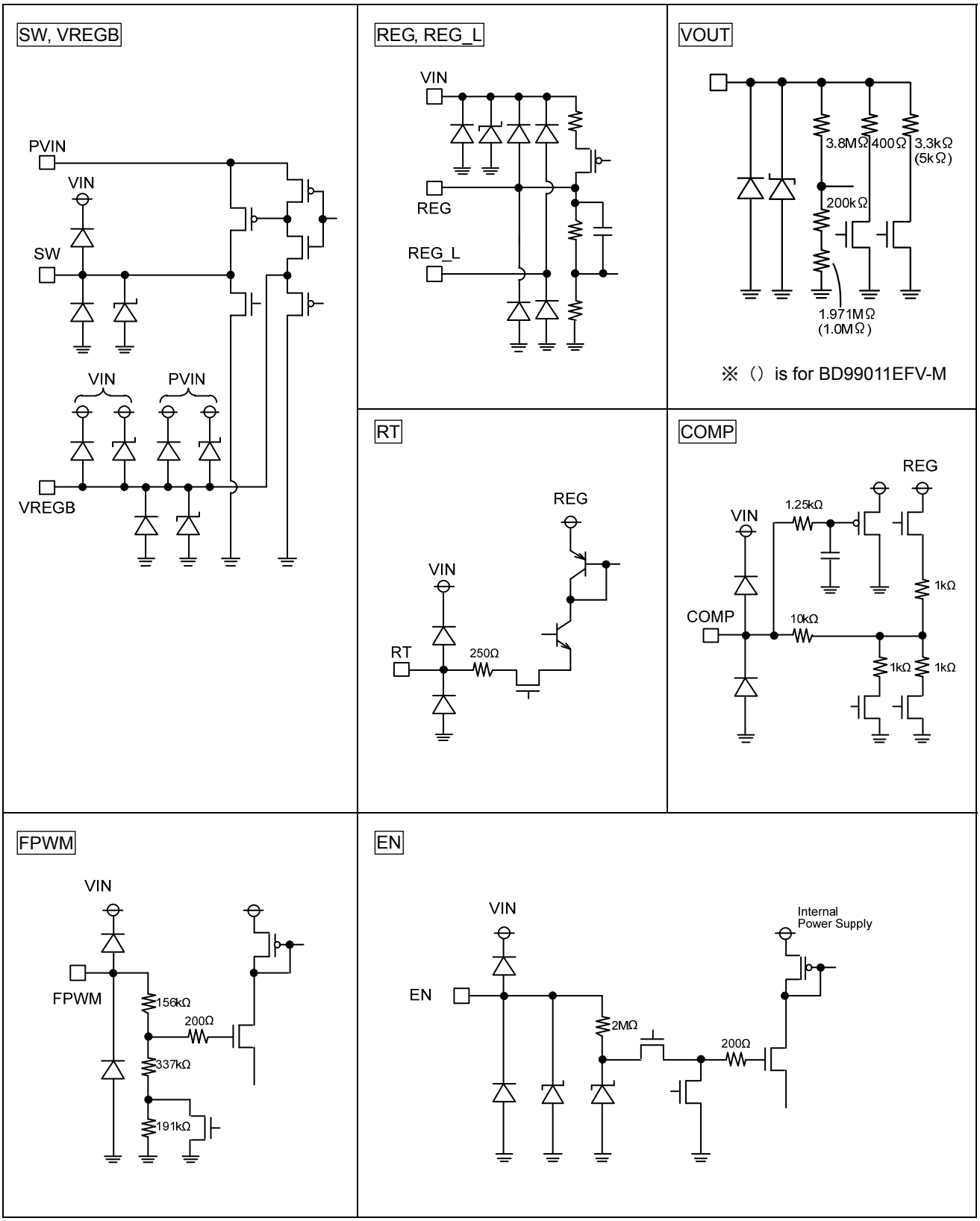


Figure 46. Equivalent circuit figure

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Operational Notes

1. Absolute maximum ratings
   Exceeding the absolute maximum rating for supply voltage, operating temperature or other parameters can result in damages to or destruction of the chip. In this event it also becomes impossible to determine the cause of the damage (e.g. short circuit, open circuit, etc). Therefore, if any special mode is being considered with values expected to exceed the absolute maximum ratings, implementing physical safety measures, such as adding fuses, should be considered.

2. GND electric potential
   Keep the GND terminal potential at the lowest (minimum) potential under any operating condition. Furthermore, excluding the SW pin, the voltage of all pin should never drop below that of GND. In case there is a pin with a voltage lower than GND implement countermeasures such as using a bypass route.

3. Power dissipation
   Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. Therefore allow for sufficient margins to ensure use within the power dissipation rating.

4. Input power supply
   Concerning the input pins VIN and PVIN, the layout pattern should be as short as possible and free from electrical interferences. In case the impedance of the input supply line is large, the resulting voltage drop at high load situation and low supply voltage will cause repeated UVLO cycles sometimes referred to as “chattering”. Therefore, the impedance of the input line should be so small that the worst case voltage drop is smaller than the UVLO hysteresis.
   To prevent damage to or destruction of the chip, the input filter which can be contain 0.5V/μs against the voltage of VIN and PNIN should be considered.

5. Electrical characteristics
   The electrical characteristics given in this specification may be influenced by conditions such as temperature, supply voltage and external components. Transient characteristics should be sufficiently verified.

6. Thermal shutdown (TSD)
   This IC incorporates and integrated thermal shutdown circuit to prevent heat damage to the IC. Normal operation should be within the power dissipation rating, if however the rating is exceeded for a continued period, the junction temperature (Tj) will rise and the TSD circuit will be activated and turn all output pins OFF. After the Tj falls below the TSD threshold the circuits are automatically restored to normal operation.
   Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

7. Inter-pin shorting and mounting errors
   Ensure that when mounting the IC on the PCB the direction and position are correct. Incorrect mounting may result in damaging the IC. Also, shorts caused by dust entering between the output, input and GND pin may result in damaging the IC.

8. In some applications, the VIN and pin potential might be reversed, possibly resulting in circuit internal damage or damage to the elements. For example, while the external capacitor is charged, the VIN shorts to the GND. For the REG and REG_L output pin use a capacitor with a capacitance with less than 100μF. We also recommend using reverse polarity diodes in series or a bypass diode between all pins and the V_{BAT} pin.

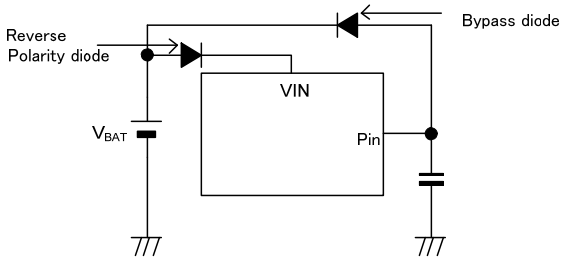


Figure 47.

9. Operation in strong electromagnetic fields
   Use caution when operating in the presence of strong electromagnetic fields, as this may cause the IC to malfunction.

10. In applications where the output pin is connected to a large inductive load, a counter-EMF (electromotive force) might occur at startup or shutdown. A diode should be added for protection.

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11. Testing on application boards
The IC needs to be discharged after each test process as, while using the application board for testing, connecting a capacitor to a low-impedance pin may cause stress to the IC. As a protection from static electricity, ensure that the assembly setup is grounded and take sufficient caution with transportation and storage. Also, make sure to turn off the power supply when connecting and disconnecting the inspection equipment.

12. GND wiring pattern
When both a small-signal GND and a high current GND are present, single-point grounding (at the set standard point) is recommended. This in order to separate the small-signal and high current patterns and to ensure that voltage changes stemming from the wiring resistance and high current do not cause any voltage change in the small-signal GND. Similarly, care must be taken to avoid wiring pattern fluctuations in any connected external component GND.

13. This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. Relations between each potential may form as shown in the example below, where a resistor and transistor are connected to a pin:
- o With the resistor, when GND＞ Pin A, and with the transistor (NPN), when GND＞Pin B:
  The P-N junction operates as a parasitic diode.
- o With the transistor (NPN), when GND＞ Pin B:
  The P-N junction operates as a parasitic transistor by interacting with the N layers of elements in proximity to the parasitic diode described above.

Parasitic diodes inevitably occur in the structure of the IC. Their operation can result in mutual interference between circuits and can cause malfunctions and, in turn, physical damage to or destruction of the chip. Therefore do not employ any method in which parasitic diodes can operate such as applying a voltage to an input pin that is lower than the (P substrate) GND.

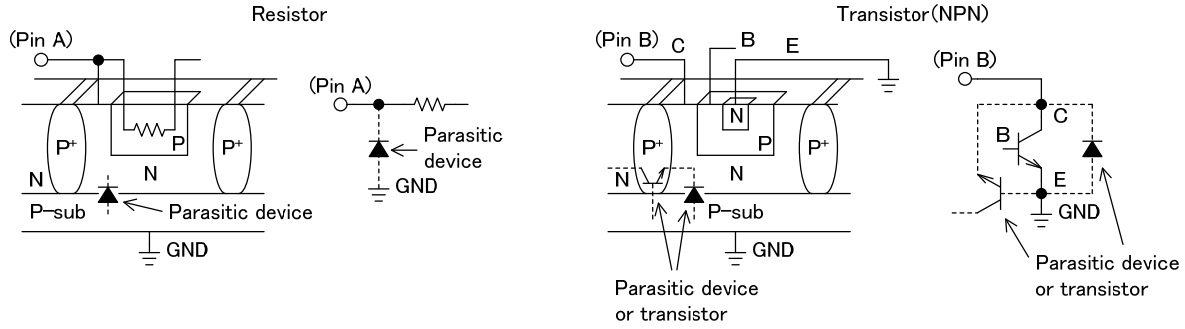


Figure 48.

14. REG PIN
REG is output that supplies the internal circuit. We do not recommend using REG for any other purpose.

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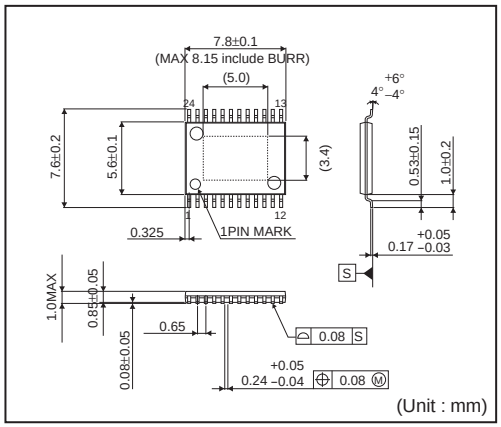
Ordering Information

B D 9 9 0 1 x E F V	ME 2

- Part Number
  99010 : 3.3V output
  99011 : 5V output
- Package
  EFV: HTSSOP-B24
- Packaging and forming specification
  E2: Embossed tape and reel

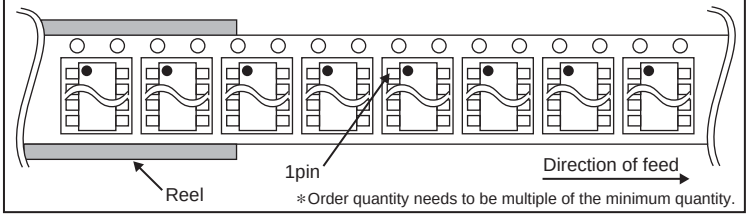
Physical Dimension Tape and Reel Information

HTSSOP-B24



<Tape and Reel information>

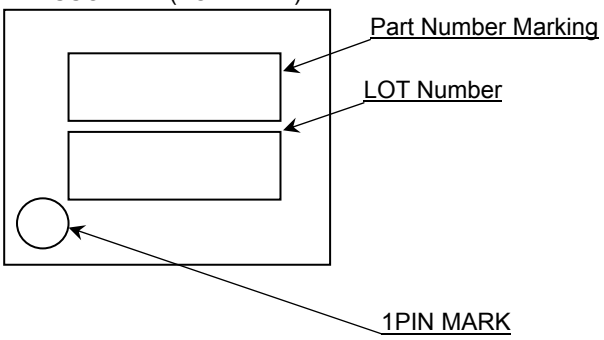
Tape	Embossed carrier tape (with dry pack)
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

Marking Diagram

HTSSOP-B24(TOP VIEW)



Part Number Marking	Output Voltage (V)
BD99010	3.3
BD99011	5.0

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Revision History

Date	Revision	Changes
28.Feb.2013	Rev.001	New Release as Draft.
23.Jun.2014	Rev.002	P.1 Key Specifications , Input Voltage Range change. (record both Absolute Maximum Ratings and Recommended Operating Ratings) Figure.1 Correct. P.4 UVLO , Correct comment. (REG Voltage→VIN Voltage). P.7 Absolute Maximum Ratings, Add parameter [PVIN-VREB voltage]. Delete comment (2) P.17,18 Change inductor's Product Name.
7.July.2014	Rev.003	P.1 Key Specifications Sentense change "AEC-Q100 qualification is in progress" ↓ "AEC-Q100 qualified"

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
   [a] Installation of protection circuits or other protective devices to improve system safety
   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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